

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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> Title of Invention

METHOD OF FORMING A THERMALLY CONDUCTIVE ARTICLE USING METAL INJECTION

Application Number:

10/605041

Confirmation Number:

2040

First Named Applicant:

Kevin McCULLOUGH Attorney Docket Number: C001CPP00404US2

Art Unit:

1775

Search string:

(T904012 or 3398322 or 3673121 or 3708387

or 40998945 or 4307147 or 4367745 or

4496475 or 4568592 or 4664971 or 4689250 or 4816184 or 5011870 or 5011872 or 5021494 or 5098610 or 5106540 or 5180513 or 5213715 or 5225110 or 5286416 or 5302456 or 5334330 or 5373046 or 5397608 or 5445308 or 5490319 or 5522962 or 5536568 or 5580493 or 5669381 or 5681883 or 5770305 or 5834337 or 5851644 or 5863467 or 5945217 or 6048919 or 4470063 or 5037590 or 5373046 or 5400505 or 5454425 or 5552214 or 5660923 or 5981085 or 6139783 or 6303096 or 20020022686 or 20020025998).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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而	3	3673121	1972-06-27	Meyer		252	511
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m	5	40998945	1978-07-04	Oehmke		428	327
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252	62.55		
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428	34.5		
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428	327		
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264	29.2		
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

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Signature

Examiner Name	Date			
Opund	6/28/04			